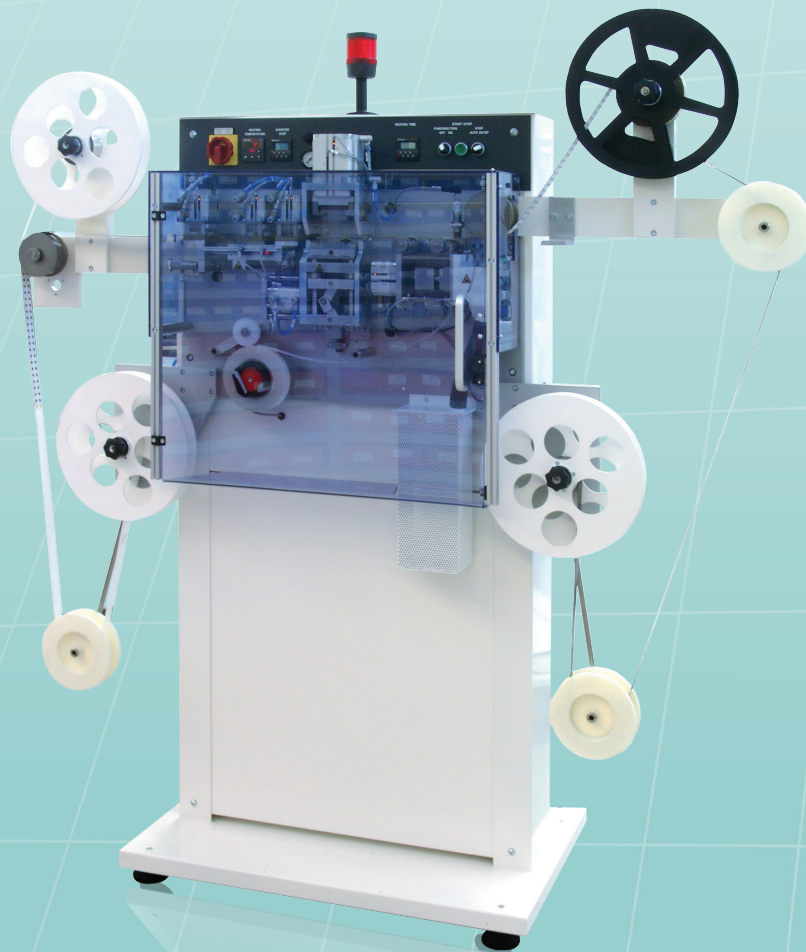


Smart card – glue tape lamination GTL600



glue tape laminating

GTL600

The Glue Tape Laminator GTL600 is used for the preparation of IC module tapes for the hot melt implanting process. In this process the hot melt tape will be punched before it will be laminated onto module tape. The standard equipment consists of a tool set

for one chip module type. The GTL600 operates as a standalone unit. Exchange kits are available for other module dimensions and additional protection foil handling is available as options.

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Applications

- chip module tape on roll up to 530 mm diameter for different chip module types and sizes

Benefits & features

- multiple hole punch tools, waste collection
- end of tape check and tension control
- small footprint
- best price-performance ratio

Technical specifications

tape specifications:

- module tape: 35mm; pitch 9.5 or 14.25
- spacer tape: 35 mm
- reel dimension: for modul tape and protection tape max 530 mm (larger size on request)
- HM-foil: Ø-inside 75 mm / Ø-outside max 200 mm
- Standart and FCOS-modules

technical data:

- laminating temperature adjustable: 100°C – 170°C
- laminating pressure adjustable: 20 - 50 N/cm²
- compressed air: 7 bar, oil-free, dry, constant, class 4 (ISO 8573-1)
- compressed air flow rate: 15 litres / min, at 7 bar
- electrical supply: 230 V, 50 Hz (other's possible), 0,5 kW with 1 x 16A fuse (time-lag)

environmental conditions:

- ambient temperature: 22°C ± 5°
- degree of relative humidity: max. 70%
- condensation of water: not allowed

machine dimensions:

- length: 880 mm
- width: 550 mm
- height: 1600 mm
- weight: 200 kg

throughput:

- output up to 7.500 chip modules/hour (M1/M3)